## RESPONSE UNDER 37 C.F.R. § 1.116 **EXPEDITED PROCEDURE - EXAMINING GROUP 1700 PATENT**

I hereby certify that on the date specified below, this correspondence is being deposited with the United States Postal Service as first-class mail in an envelope addressed to Mail Stop RCE, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

Date

DEC 18 2006

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Appl. No. : 09/974,958

Confirmation No. : 7582

Applicants: Vernon M. Williams et al.

: October 10, 2001

Attorney Docket No.: 501062.01

Art Unit : 1722 Customer No.

: 27,076

Examiner: Robert B. Davis

Title

Filed

: LEADFRAME AND METHOD FOR REDUCING MOLD COMPOUND ADHESION

**PROBLEMS** 

Mail Stop RCE Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

## RESPONSE UNDER 37 C.F.R. § 1.116

Sir:

Applicants acknowledge receipt of the Advisory Action dated December 1, 2006, and herewith petitions the Commissioner for Patents under 37 C.F.R. § 1.136(a)(3) for a onemonth extension of time for filing this response from December 7, 2006, to January 7, 2007. Submitted herewith is a check in the amount of \$910, which includes \$120 to cover the cost of the extension. Any deficiency or overpayment should be charged or credited to Deposit Account No. 50-1266.

Please amend the above-identified application as follows:

Amendments to the Claims are reflected in the listing of claims which begins on page 2 of this paper.

Remarks begin on page 8 of this paper.

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